

Tomomi Sakata

List of Publications by Year in descending order

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all docs

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docs citations

36
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202
citing authors

#	ARTICLE	IF	CITATIONS
1	Luminescent properties of a polymeric copper(I)-bromide complex in a PMMA film. Japanese Journal of Applied Physics, 2020, 59, 077001.	1.5	2
2	Synthesis and characterization of Cu(I) isocyanide complexes exhibiting reversible luminescence. Japanese Journal of Applied Physics, 2018, 57, 081601.	1.5	2
3	Reversible Formation of an Inter-Molecular Compound Comprising 3- β -Amino-9-fluorenyl-5-imidazolidinone-2,4-dithione and Benzene. Heterocycles, 2018, 96, 2087.	0.7	1
4	Nonlinear Oscillation for a Millimeter-Sized Vibrational Energy Harvester with Ethylene Tetrafluoroethylene Electret. IEICE Transactions on Communications, 2016, E99.B, 1677-1686.	0.7	0
5	Nonlinear oscillation for a millimeter-sized electrostatic energy harvester. , 2015, , .		1
6	Monolithically integrated MEMS mirror array with low electrical interference in wavelength-selective switches. Precision Engineering, 2013, 37, 897-901.	3.4	1
7	A physical modeling and long-term measurement of tilting angle drift caused by dielectric surface charging in MEMS micromirrors. , 2013, , .		5
8	Deformation and Restoration of Shape in Microelectromechanical System Membrane. ECS Journal of Solid State Science and Technology, 2013, 2, Q211-Q213.	1.8	0
9	Synchronized Multiple-Array Vibrational Device for Microelectromechanical System Electrostatic Energy Harvester. Japanese Journal of Applied Physics, 2012, 51, 05EE01.	1.5	4
10	Selective Removal of Dry-Etching Residue Derived from Polymer Sacrificial Layer for Microelectromechanical-System Device Fabrication. Japanese Journal of Applied Physics, 2012, 51, 096502.	1.5	2
11	Impedance-Sensing Circuit Techniques for Integration of a Fraud Detection Function Into a Capacitive Fingerprint Sensor. IEEE Sensors Journal, 2012, 12, 1393-1401.	4.7	15
12	Monolithic integrated MEMS mirror array module towards low electrical interference. , 2012, , .		1
13	Removal of Gold Oxide by Low-Temperature Hydrogen Annealing for Microelectromechanical System Device Fabrication. Japanese Journal of Applied Physics, 2012, 51, 066501.	1.5	3
14	Synchronized Multiple-Array Vibrational Device for Microelectromechanical System Electrostatic Energy Harvester. Japanese Journal of Applied Physics, 2012, 51, 05EE01.	1.5	3
15	Removal of Gold Oxide by Low-Temperature Hydrogen Annealing for Microelectromechanical System Device Fabrication. Japanese Journal of Applied Physics, 2012, 51, 066501.	1.5	0
16	128 \times 128 three-dimensional MEMS optical switch module with simultaneous optical path connection for optical cross-connect systems. Applied Optics, 2011, 50, 4037.	2.1	25
17	Fabrication of a microelectromechanical system mirror array and its drive electrodes for low electrical interference in wavelength-selective switches. IEJ Transactions on Electrical and Electronic Engineering, 2011, 6, 384-389.	1.4	5
18	New H-shape soft torsion spring and its micro mirror application. , 2010, , .		3

#	ARTICLE	IF	CITATIONS
19	Electrically separated two-axis MEMS mirror array module for wavelength selective switches. , 2009, , .		14
20	High-aspect-ratio gold electrodes fabricated by thick-multilevel interconnection technology for electrical isolation of MEMS mirrors in wavelength-selective switches. , 2009, , .		0
21	Cleaning of Gold Interconnection Surface by Low-temperature Hydrogen Annealing for MEMS Device Fabrication. ECS Transactions, 2009, 16, 29-35.	0.5	0
22	Surface Cleaning of Gold Structure by Annealing during Fabrication of Microelectromechanical System Devices. Japanese Journal of Applied Physics, 2009, 48, 026501.	1.5	17
23	A Fingerprint Sensor with Impedance Sensing for Fraud Detection. , 2008, , .		11
24	Monolithic Integration Fabrication Process of Thermoelectric and Vibrational Devices for Microelectromechanical System Power Generator. Japanese Journal of Applied Physics, 2007, 46, 6062-6067.	1.5	16
25	Electrodeposition of Water-Repellent Organic Dielectric Film as an Anti-Sticking Coating on Microelectromechanical System Devices. Japanese Journal of Applied Physics, 2007, 46, 6454-6457.	1.5	2
26	Vacuum Annealing of Gold Electrodes for Surface Cleaning in MEMS Device Fabrication. , 2007, , .		0
27	Conformal Coating of Organic Dielectric Film on Gold Electrodes in Microelectromechanical System Devices by Electrodeposition. IEEJ Transactions on Sensors and Micromachines, 2007, 127, 253-257.	0.1	8
28	Novel Structure and Fabrication Process for Integrated RF Microelectromechanical-System Technology. Japanese Journal of Applied Physics, 2006, 45, 6849-6853.	1.5	16
29	Selective Electrodeposition Technology for Organic Insulator Films on Microelectromechanical-System Structures. IEEJ Transactions on Sensors and Micromachines, 2006, 126, 14-18.	0.1	5
30	Electrodeposition of Organic Dielectric Film and Its Application to Vibrational Microelectromechanical System Devices. Japanese Journal of Applied Physics, 2006, 45, 5646-5649.	1.5	10
31	Novel Packaging Technology for Microelectromechanical-System Devices. Japanese Journal of Applied Physics, 2005, 44, 8177-8181.	1.5	7
32	Anti-Sticking Effect of Organic Dielectric Formed by Electrodeposition in Microelectromechanical-System Structures. Japanese Journal of Applied Physics, 2005, 44, 5732-5735.	1.5	3
33	<title>Optical switch based on thermocapillarity</title>. , 2001, , .		1
34	Improvement of switching time in a thermocapillarity optical switch. , 2001, , .		4
35	Reflection-type 2Å–2 optical waveguide switch using the Goos-Hänchen shift effect. Applied Physics Letters, 2000, 76, 2841-2843.	3.3	88
36	Measurement of the enhancement factor of chemically induced dynamic nuclear polarization in the photolysis of dibenzyl ketone: determination of the spin multiplicity of the precursor. The Journal of Physical Chemistry, 1991, 95, 8671-8676.	2.9	9